

AMENDMENTS TO THE CLAIMS

Please amend the claims as follows:

Listing of Claims:

Claim 1 (Currently Amended): A cooling device for cooling an electronic element ~~configured to produce concentrated heat by a flow of a cooling medium~~, comprising:

a cooling portion configured to cool the electronic element by a flow of the cooling medium;

a first flow channel disposed upstream of the cooling portion ~~electronic element~~ in the flow of the cooling medium;

a second flow channel disposed downstream of the cooling portion ~~electronic element~~ in the flow of the cooling medium; and

an active heat transport element comprising a heat intake portion and a heat outlet portion, the active heat transport element configured to conduct heat from the heat intake portion to the heat outlet portion, the heat intake portion being upstream of the cooling portion and thermally connected with the first flow channel so as to conduct heat from the cooling medium before the cooling medium arrives at the cooling portion, the heat outlet portion being downstream of the cooling portion and thermally connected with the second flow channel so as to conduct heat to the cooling medium.

Claim 2 (Cancelled).

Claim 3 (Original): The cooling device according to claim 2, wherein:

the first flow channel, the second flow channel and the cooling portion are integrally formed.

Claim 4 (Original): The cooling device according to claim 1, wherein:
the active heat transport element is a Peltier element.

Claim 5 (Currently Amended): An electronic device including an electronic element producing concentrated heat, the electronic device includes a first chassis for housing the electronic element and a second chassis connected with the first chassis by means of a hinge so as to be foldable, comprising:

a cooling medium circuit comprising a pump for circulation of a cooling medium between the first chassis and the second chassis;

a cooling device housed in the first chassis and connected with the cooling medium circuit, the cooling device comprising;

an active heat transport element comprising a heat intake portion and a heat outlet portion, the active heat transport element configured to conduct heat from the heat intake portion to the heat outlet portion;

~~a first flow channel thermally connected with the heat intake portion so as to conduct heat from the cooling medium to the heat intake portion;~~

a cooling portion for heat exchange between the electronic element and the cooling medium; and

~~a second flow channel thermally connected with the heat outlet portion so as to conduct heat from the heat outlet portion to the cooling medium;~~

a flow path including a first flow channel and a second flow channel, the flow path linked with the cooling portion, and configured to conduct the cooling medium from the first flow channel through the cooling portion to the second flow channel, the first flow channel being upstream of the cooling portion and thermally connected with the heat intake portion so as to conduct heat from the cooling medium to the heat

intake portion before the cooling medium arrives at the cooling portion, the second flow channel being downstream of the cooling portion and thermally connected with the heat outlet portion to the cooling medium; and

an auxiliary heat radiation unit connected to the active heat transport element;

wherein the cooling medium flows from the first flow channel via the cooling portion to the second flow channel; and

a heat radiation unit housed in the second chassis and connected with the cooling medium circuit so as to radiate heat transported from the cooling device.

Claim 6 (Previously Presented): The cooling device according to Claim 1, wherein fins are arranged on the heat intake portion and on the heat outlet portion of the active heat transportation unit, configured to be thermally connected to the active heat transportation unit.

Claim 7 (New): The cooling device according to Claim 1, wherein the first flow channel, the second flow channel, and the cooling portion form a flow path, the flow path being configured to conduct the cooling medium from the first flow channel through the cooling portion to the second flow channel.